Interface Electronics

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Outline

- > Up to now constraints
- Digital part
- > Analogue part
- > Backplane
- > Vacuum board
- > Quadrants



DESY responsibilities

- Digital part
- > Analogue part
- > Backplane
- > Vacuum board
- > Quadrant

- DESY: FEA-group, M.Zimmer et.al.
- DESY: FEB-group, P.Göttlicher et al.
- DESY: FEB-Group P.Göttlicher et. al.
- DESY: FSDT-Group H.Graafsma et. al.
- DESY: FEA/FEB-groups.....



Mechanical baseline for the design



Baseline was:

- Everything should fit behind the sensor
- Backplane as vacuum barrier
- Control and ASIC-power from the quadrant
- Two parallel analogue boards
- Rails for guiding the motherboards with a width of 95mm



Peter Göttlicher | AGIPD consortium | September 27th , 2012 | Page 4

Digital part





Digital part: Performance



4 x 4 x 3.125Gbit/s

Fast Memory Access, OK.



Short distances with 4 x 10Gbit/s

No bit errors within a day: Bit error <10⁻¹⁵

Coded:

- 10GbE/UDP
- DDR2-Memory Access
- ADC, except small modification for datasheet changes

Well open eyes



Backend: Train builder

Developped:

- ATCA @ STFC
- FMC @ DESY-FEA For all XFEL-detectors

First board for testing and Work on PC connection @ XFEL

> Links for 8 Frontends, ¹/₂ of 1-MegaPixel or 8 outputs

DDR2- SODIMM for trains

QDR-II SRAM e.g. geometry sorting





Train builder: Requests presorted geometry



Analogue Part

Board width "NOW"

- Active within 80mm
- Graphic 85mm Will increase to 95mm
- EMI strips to mechanical rails
- New mechanical constraints?

Board length:

- 30 cm allowed
- Likely to get shorter
- Power giving up to gain length?
 Would fit into 30cm



Analogue part: Simulated performance



Mother Board

- Layout for the dense part done
- Infrastructual part will be optimized for space in the circuit diagram
- Layout until end October

That allows to operate ONE row of the 8 ASIC's

Daughter board

- Dense part is reused from mother
- So start than with the copy from Mother while mother is in production



What constraints are up to date?

- Vacuum tide burried vias/micro via is not seen as a problem
- SAMTEC would have also a 400-pin or 500-pin SMD-connector right angle.

Need the input from the vacuum board design Layouter is the same as the analogue boards!



Vacuum board

What are the tasks?

- ASIC-designer requests to have the voltage regulated close to the ASIC's: 16 voltage regulators up to 2A.
- A negative voltage for the ASIC: current, common ?
- A positive voltage for the pixel-input-protection Charge/train? Voltage? Current? Common?
- Own monitoring via I2C from quadrant
- Three LVDS-line buffering for the ASIC control
- Generating a ASIC-select from commands of I2C for booting. While running all in parallel
- Passing the ASIC analogue outs through all that digital/power

Mechanics?



Quadrant



- Power guidance for ASIC's
- Control signals receiver from C&C
- Slow Control receiving from PC

C&C has specified their protocol

- Including a bunch-reject with random time delay
- Based on 99MHz system clock synchronized to the bunches

Prototype will be based on ARM9 and XILINX Evaluation boars.

After settling experience + specifications Development for dedicated geometry.



Summary

- Digital Active board in hand Basing blocks for ADC and data link and Detector specific blocks getting first ideas, what needed, e.g. sorting
- Digital mother board will be started very soon:
 - Last chance for mechanics constraints changes
 - Baseline: Everything behind the sensor, when going to 1MegaPixel rail system with electrical conductive rails
 - Reuse of multi-project digital board only for single module and if more height.
- Analogue Mother board
 - major part is routed
 - Baseline: everything behind sensor with conductive rails
- Analogue daughter will follow
- Backplane needs more inputs and layouter the same as analogue
- Vacuum board, no explicite design started
- Quadrant start with evaluation boards

